July 13th, 2012 SuperB-SVT meeting

update on Strasbourg activities on CMOS pixel developments

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MIMOSA-32: 0.18 µm technology exploration

- Submitted in Oct. 2011, delivered in January 2012.
- Technology:
 - · epitaxial layer: 18 μ m thick, High-Resistivity 1-5 k Ω .cm.
 - · quadruple well: deep P-type skin embedding N-well hosting P-MOS transistors.
 - · 4 Metal Layers (6 ML at next submission in 2012).
- Prototype sub-divided in several blocks:
 - Explore pixel sizes: 20x20, 20x40 and 20x80 μm^2 .
 - Explore charge amplification / collection systems: diode sizes ~9-15 µm², N-MOS and P-MOS transistor based amplifiers.
 - Explore discrimination: I sub-array of 128 columns with I discriminator at each column end, and one sub-array with in-pixel discrimination (16x80 µm² pixels).
 - → total surface ~ 43 mm².
- Several lab. test results already presented during previous SVT meetings:
 - · charge collection efficiency,
 - · noise,
 - ionising radiation tolerance (3 MRad, 30 °C).
 - \rightarrow encouraging results.



MIMOSA-32: non-ionising irradiation (I)

- Several MIMOSA-32 chips exposed to 1 MeV neutrons (20x20 µm²): integrated doses of 0.3 - 1.0 - 3.0 x10¹³ n_{eq} / cm².
- Lab. tests with ⁵⁵Fe source, chips are cooled at +15 °C.



→ signal seems not to be degraded by traps induced by bulk damages after non ionising radiations.



→ evolution with fluence seems due to a typical effect of leakage current.
Noise increase modest up to fluences of Ix10¹³ n_{eq} / cm².

MIMOSA-32: non-ionising irradiation (2)

• Test in June 2012 with 60 GeV π^{-} beam (SPS-T4/H6):

S/N ~ 32 before irradiation \Rightarrow S/N ~ 26 after 1.0x10¹³ n_{eq} / cm² (at 30 °C). for 20x20 µm² pixels.



• Other pixel sizes will be tested at CERN with beam (19-25 July 2012).